

# Product Change Notification

The information below reflects a change that is being implemented.

Notice Date: 04/23/2001

Product Category: 24xxx

Notification Subject: Change #303 - 128K & 256K EEPROM

Notification Body:  
CCB #: 303

Projected Ship Date of Revised Device:  
5/30/01

## Description of Change

The I2C EEPROMs with densities of 128K and 256K bits will be moved from the current 121K (0.7 micron) fabrication process to the new 150K (0.5 micron) process. In order to continue receiving devices from the current 121K process, the revised part numbers listed below shall be used. If an order is received using the current part numbers, the new devices from the 150K process will be shipped. The devices affected include all voltages, temperatures and packages. For clarification, the part numbers for the 14-lead TSSOP package in the 128K density also changed, so it is listed separately in column 3.

### PART# REVISED PART # (121K)

24LC128-x/xx 24LC128-x/xxRVA  
24AA128-x/xx 24AA128-x/xxRVA  
24FC128-x/xx 24FC128-x/xxRVA

### PART# REVISED PART # (121K)

24LC256-x/xx 24LC256-x/xxRVA  
24AA256-x/xx 24AA256-x/xxRVA  
24FC256-x/xx 24FC256-x/xxRVA

### PART# REVISED PART # (121K)

24LC128-x/ST 24LC128-x/ST14RVA  
24AA128-x/ST 24AA128-x/ST14RVA

## Impacts to Data Sheet:

New packages were added to the data sheets.

Reason for Change:

A new die shrink on an 8-inch wafer fabrication process is being added, which will give us the ability to increase capacity and offer devices in smaller packages.

Markings to Distinguish Revised From Unrevised Devices: (e.g.: Date Code, Device Marking, Ship Container Marking)

See description of change above

Summary of Qualification Results:

The qualification results are available under Qualification Report # C0301384

Additional Comments

The revised part numbers listed above will give customers the option of ordering memory from the older process without interruption.